DELL ™ OPTIPLEX [™] 390

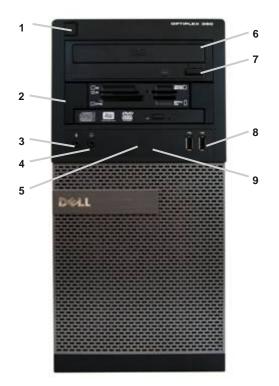
TECHNICAL GUIDEBOOK— INSIDE THE OPTIPLEX 390



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MINI TOWER COMPUTER (MT) VIEW

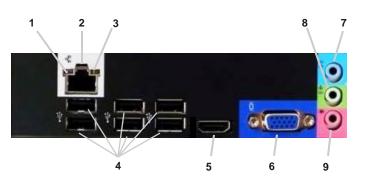


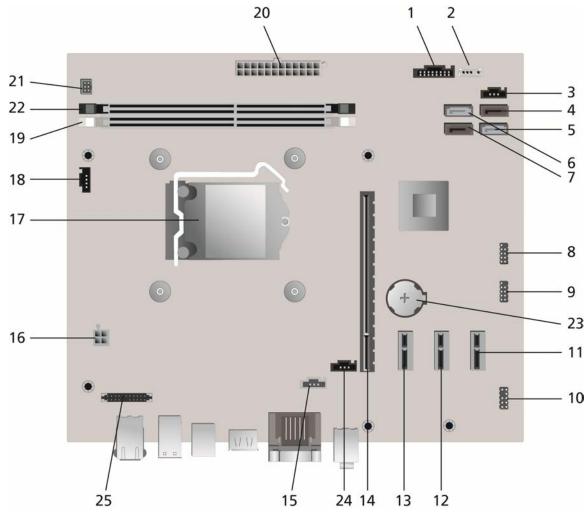
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FRONT VIEW				
1	Power Button, Power Light	6	Optical Drive (optional)	
2	Optical Drive Bay (optional)	7	Optical Drive Eject Button	
3	Microphone Connector	8	USB 2.0 Connectors (2)	
4	Headphone Connector	9	Drive Activity Light	
5	Diagnostic Lights (4)			

BACK VIEW				
10	Power Supply Diagnostic Light	14	Expansion Card Slots(4)	
11	Power Supply Diagnostic Button	15	Security Cable Slot	
12	Power Connectors	16	Padlock Ring	
13	Back Panel Connectors			

BACK PANEL CONNECTORS				
1	Link Integrity Light	6	VGA Connector	
2	Network Connector	7	Line-in Connector	
3	Network Activity Light	8	Line-out Connector	
4	USB Connectors (6)	9	Microphone Connector	
5	HDMI Connector			

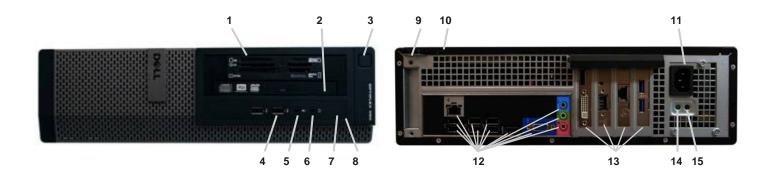




MT System Board Components

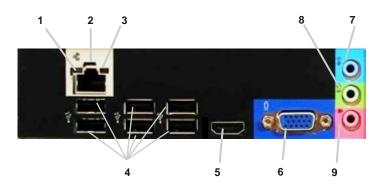
Number	Name	Number	Name
1	Front IO connector (FRONTPANEL))	14	PCI-e 16x Connector (SLOT1)
2	Internal Speaker Connector (INT_SPKR)	15	System fan Connector (FAN_SYS2)
3	System fan Connector (FAN_SYS1)	16	P2 Power Connector(ATX12V)
4	SATA 1 Connector(SATA1)	17	CPU Socket Connector (U27CPU)
5	SATA 0 Connector(SATA0)	18	CPU fan Connector (FAN_CPU)
6	SATA 2 Connector(SATA2)	19	Memory Connector(DIMM1)
7	SATA 3 Connector(SATA3)	20	P1 power Connector (ATX)
8	Internal USB Connector (USBF1)	21	Power Switch Connector (PWRSW1)
9	Internal USB Connector (USBF1)	22	Memory Connector(DIMM2)
10	Internal Audio Connector (AUDIOF1)	23	Battery Connector (BT1)
11	PCI-e 1x Connector (SLOT4)	24	Intrusion Switch Connector (Intruder)
12	PCI-e 1x Connector (SLOT3)	25	KB/MS COM Connector (KBMSCOM1)
13	PCI-e 1x Connector (SLOT2)		

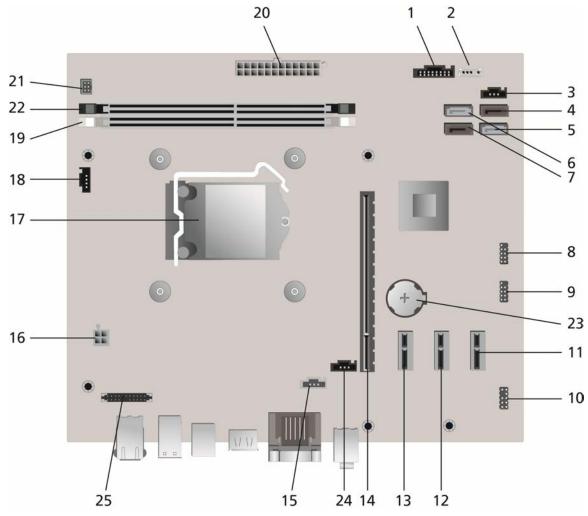
DESKTOP COMPUTER (DT) VIEW



FRONT VIEW		BACK VIEW					
1	Optical Drive	5	Microphone Connector	9	Padlock Ring	13	Expansion Card Slots(4)
2	Optical Drive Eject Button	6	Headphone Connector	10	Security Cable Slot	14	Power Supply Diagnostic Light
3	Power Button, Power Light	7	Drive Activity Light	11	Power Connectors	15	Power Supply Diagnostic Button
4	USB Connectors (2)	8	Diagnostic Lights (4)	12	Back Panel Connectors		

BACK PANEL CONNECTORS				
1	Link Integrity Light	6	VGA Connector	
2	Network Connector	7	Line-in Connector	
3	Network Activity Light	8	Line-out Connector	
4	USB Connectors (6)	9	Microphone Connector	
5	HDMI Connector			

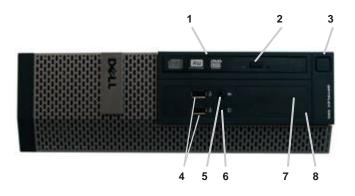


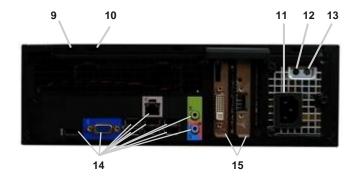


DT System Board Components

Number	Name	Number	Name
1	Front IO connector (FRONTPANEL))	14	PCI-e 16x Connector (SLOT1)
2	Internal Speaker Connector (INT_SPKR)	15	System fan Connector (FAN_SYS2)
3	System fan Connector (FAN_SYS1)	16	P2 Power Connector(ATX12V)
4	SATA 1 Connector(SATA1)	17	CPU Socket Connector (U27CPU)
5	SATA 0 Connector(SATA0)	18	CPU fan Connector (FAN_CPU)
6	SATA 2 Connector(SATA2)	19	Memory Connector(DIMM1)
7	SATA 3 Connector(SATA3)	20	P1 power Connector (ATX)
8	Internal USB Connector (USBF1)	21	Power Switch Connector (PWRSW1)
9	Internal USB Connector (USBF1)	22	Memory Connector(DIMM2)
10	Internal Audio Connector (AUDIOF1)	23	Battery Connector (BT1)
11	PCI-e 1x Connector (SLOT4)	24	Intrusion Switch Connector (Intruder)
12	PCI-e 1x Connector (SLOT3)	25	KB/MS COM Connector (KBMSCOM1)
13	PCI-e 1x Connector (SLOT2)		

SMALL FORM FACTOR COMPUTER (SFF) VIEW

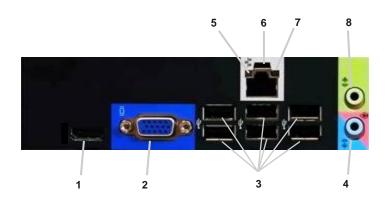


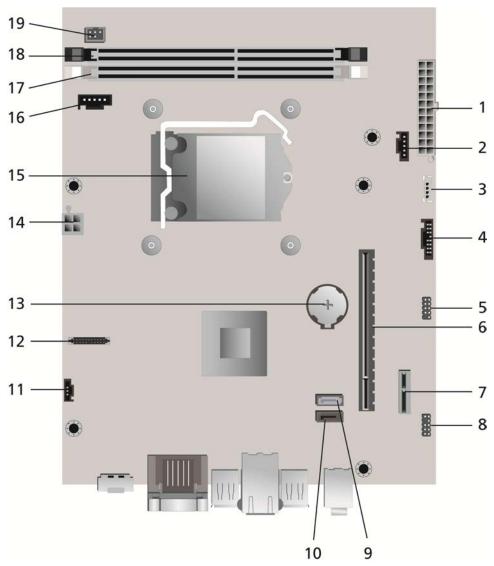


FRONT VIEW				
1	Optical Drive	5	Microphone Connector	
2	Optical Drive Eject Button	6	Headphone Connector	
3	Power Button, Power Light	7	Diagnostic Lights (4)	
4	USB 2.0 Connectors (2)	8	Drive Activity Light	

BA	CK VIEW		
9	Padlock Ring	13	Power Supply Diagnostic Light
10	Security Cable Slot	14	Back Panel Connectors
11	Power Connectors	15	Expansion Card Slots(2)
12	Power Supply Diagnostic Button		

BACK PANEL CONNECTORS				
1	HDMI Connector	5	Link Integrity Light	
2	VGA Connector	6	Network Connector	
3	USB Connectors (6)	7	Network Activity Light	
4	Line-in/Microphone Connector	8	Line-out Connector	





SFF System Board Components

Number	Name	Number	Name
1	P1 power Connector (ATX)	12	KB/MS COM Connector (KBMSCOM1)
2	System fan Connector (FAN_SYS)	13	Battery Connector (BT1)
3	Internal Speaker Connector (INT_SPKR)	14	P2 Power Connector(ATX12V)
4	Front IO connector (FRONTPANEL)	15	CPU Socket Connector (U27CPU)
5	Internal USB Connector (USBF1)	16	CPU fan Connector (FAN_CPU)
6	PCI-e 16x Connector (SLOT1)	17	Memory Connector(DIMM1)
7	PCI-e 1x Connector (SLOT2)	18	Memory Connector(DIMM2)
8	Internal Audio Connector (AUDIOF1)	19	Power Switch Connector (PWRSW1)
9	SATA 0 Connector(SATA0)		
10	SATA 1 Connector (SATA1)		
11	Intrusion Switch Connector (Intruder)		

MARKETING SYSTEM CONFIGURATIONS

NOTE: Offerings may vary by country. For more information regarding the configuration of your computer, click Start>Help and Support and select the option to view information about your computer.

OPERATING SYSTEM

	МТ	DT	SFF		
Windows 7® operating system	Microsoft® Windows 7® Home Basic SP1 (32 and 64 bit), Microsoft® Windows 7® Home Premium SP1 (32 and 64 bit), Microsoft® Windows 7® Professional SP1 (32 and 64 bit), Microsoft® Windows 7® Ultimate SP1 (32 and 64 bit),				
Windows Vista® operating system	Windows Vista® Home Basic SP2 (32 bits), Windows Vista® Business SP2 (32 and 64 bit), Windows Vista® Ultimate SP2 (32 bit)				
Windows XP® operating system	Basic Driver support only via Dell.com				
Other FreeDOS for N-series Ubuntu® Linux version 10.10 (China only)					
OS Media Support (optional)	Х	Х	Х		

CHIPSET

	МТ	DT	SFF	
Chipset	Intel H61 Express Chipset			
Non-volatile memory on chipset				
BIOS Configuration SPI (Serial Peripheral Interface) 32Mbit (4MB) located at SPI_FLASH on chipset			pset	
NIC EEPROM LOM configuration contained within SPI_FLASH – no dedic LOM EEPROM			SH — no dedicated	

PROCESSOR

NOTE: Global Standard Products (GSP) are a subset of Dell's relationship products that are managed for availability and synchronized transitions on a worldwide basis. They ensure the same platform is available for purchase globally. This allows customers to reduce the number of configurations managed on a worldwide basis, thereby reducing their costs. They also enable companies to implement global IT standards by locking in specific product configurations worldwide. The following GSP processors identified below will be made available to Dell customers.

NOTE: Processor numbers are not a measure of performance. Processor availability subject to change and may vary by region/ country.

	МТ	DT	SFF
Intel® Quad Core™ i5 Processors			
Intel® Core™ i5 2400 / 3.10GHz, 6M, VT-x, 95W	X-GSP	X-GSP	X-GSP
Intel® Dual Core™ i3 Processors			
Intel® Core™ i3 2130 / 3.40GHz, 3M, VT-x, 65W	Available in Q4 2011	Available in Q4 2011	Available in Q4 2011
Intel® Core™ i3 2120 / 3.30GHz, 3M, VT-x, 65W	Х	Х	Х
Intel® Core™ i3 2100 / 3.10GHz, 3M, VT-x, 65W	Х	Х	Х
Intel® Pentium® Dual Core Processors			
Intel® Pentium Dual Core™ G850 / 2.90GHz, 3M, VT-x, 65W	Х	Х	Х
Intel® Pentium Dual Core™ G840 / 2.80GHz, 3M, VT-x, 65W	Х	х	Х
Intel® Pentium Dual Core™ G630 / 2.70GHz, 3M, VT-x, 65W	Available in Q4 2011	Available in Q4 2011	Available in Q4 2011
Intel® Pentium Dual Core™ G620 / 2.60GHz, 3M, VT-x, 65W	Х	Х	Х
Intel® Celeron® Processors			
Intel® Celeron Dual Core™ G530 / 2.40GHz, 2M, VT-x, 65W	Available in Q4 2011	Available in Q4 2011	Available in Q4 2011
Intel® Celeron Single Core™ G440 / 1.60GHz, 1M, VT-x, 65W	Available in Q4 2011	Available in Q4 2011	Available in Q4 2011

MEMORY

NOTE: Memory modules should be installed in pairs of matched memory size, speed, and technology. If the memory modules are not installed in matched pairs, the computer will continue to operate, but with a slight reduction in performance. The entire 8GB memory range is available to 64-bit operating systems.

	MT	DT	SFF		
Type: DDR3 Synch DRAM Non-ECC Memory		1333MHz			
DIMM Slots	2	2	2		
DIMM Capacities	Up to 4GB	Up to 4GB	Up to 4GB		
Minimum Memory	1GB	1GB	1GB		
Maximum System Memory	8GB ¹	8GB ¹	8GB ¹		
Memory configurations					
8GB ¹ DDR3, 1333MHz, (2 DIMM)	Х	Х	Х		
4GB ¹ DDR3, 1333MHz, (1 DIMM)	Х	Х	Х		
3GB DDR3, 1333MHz, (2 DIMM)	Х	Х	Х		
2GB DDR3, 1333MHz, (1 DIMM)	Х	Х	Х		
1GB DDR3, 1333MHz, (1 DIMM)	Х	Х	Х		

¹The total amount of available memory will be less than 4GB. The amount less depends on the actual system configuration. To fully utilize 4GB or more of memory requires a 64-bit enabled processor and 64-bit operating system.

HARD DRIVES

	МТ	DT	SFF
Bays:			
5.25-inch Optical Bay Supported (External)	2	1	1
Optical Drives Supported (maximum)	2	1	1 (slim-line)
Hard Drive Bay Supported (Internal)	2	1	1
Hard Drives Supported 3.5"(maximum)	2	1	1
Interface:	·		
SATA 2.0	4	4	2
SATA 3.0 (chipset does not support)			
3.5" Hard Drives:			
1TB ¹ SATA 7200 RPM HDD	Х	Х	Х
500GB ¹ SATA 7200 RPM HDD	Х	Х	Х
320GB ¹ SATA 7200 RPM HDD	Х	Х	Х
250GB ¹ SATA 7200 RPM HDD	Х	Х	Х

REMOVABLE STORAGE

	МТ	DT	SFF	
Optical Drive: (SFF require slim-line optical drive)				
DVD+/-RW ² SATA 1.5Gbit/s	Х	Х	Х	
DVD-ROM ³ SATA 1.5Gbit/s	Х	Х	Х	
Media Card Reader: (requires slim line optical)				
Dell 19 in 1 Media Card Reader	Х	Х		

NOTE: Dell 19 in 1 Media Card Reader (MCR) is supported via a F5 to F3 bay converter on the MT and DT and may require a slim

¹ For hard drives, GB means 1 billion bytes; actual capacity varies with preloaded material and operating environment and will be less.

² Discs burned with this drive may not be compatible with some existing drives and players; using DVD+R media provides maximum compatibility.

³ DVD-ROM drives may have write-capable hardware that has been disabled via firmware modifications.

SYSTEM EXPANSION SLOTS

NOTE: See Detailed Engineering Specifications for maximum card dimensions.

NOTE: Add in card location and priority: PCIe x16: GFX, USB 3.0, Serial, Parallel/Serial, NIC, Wireless; PCIe x1: USB 3.0, Serial,

	МТ	DT	SFF
PCIe x16 Slot	1	1	1
PCIe x1 Slot	3	3	1
Serial ATA (SATA) connectors	4	4	2

GRAPHICS/VIDEO CONTROLLER

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	МТ	DT	SFF
Intel HD Graphics [with Celeron/Pentium class CPU-GPU combo] Intel HD Graphics 2000[with iCore Dual/Quad core class CPU- GPU combo]	Integrated on CPU		
Enhanced Graphic/Video Options			
1GB AMD RADEON HD 6450 with DP and DVI	Optional FH card Optional LP card		LP card
512MB AMD RADEON HD 6350 with dual DVI or dual VGA (adapters convert DMS-59 connector to dual DVI or dual VGA)	Optional FH card	Optional	LP card

EXTERNAL PORTS/CONNECTORS

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards. See chassis diagrams section for port/ connector locations

	МТ	DT	SFF	
USB 2.0 (1 internal on MT and DT)		2 Front, 6 Rear		
Parallel and Serial port via optional PCIex1 card	Optional FH card			
Parallel port via optional PCIex1 card		Optiona	l LP card	
Serial and PS/2 via optional dongle	Optional FH card	Optiona	l LP card	
Network Connector (RJ-45)		1 Rear		
USB 3.0 via optional PClex1 card	Optional FH card	Optional FH card Optional LP card		
Video:				
VGA		1 Rear		
НДМІ		1 Rear		
Audio:				
Line in for microphone		1 Front, 1 Rear		
Line in for stereo	1 Re	1 Rear		
Line out for headphones or speakers		1 Front, 1 Rear		

COMMUNICATIONS - NETWORK ADAPTER (NIC)

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	МТ	DT	SFF
Integrated Realtek LOM	Integrated on system board		
Broadcom NetXtreme 10/100/1000 PCIe Gigabit Networking Card	Card Optional card		

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

COMMUNICATIONS - WIRELESS

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

	мт	DT	SFF
Dell Wireless 1520 PCIe WLAN card (802.11n)	Optional card		

AUDIO AND SPEAKERS

MT DT				
Conexant CX20641 High Definition Audio Codec	Integrated on system board			
Internal Dell Business Audio Speaker	Optional			
Dell AX210 2.0 Desktop Speakers	X210 2.0 Desktop Speakers Optional			
Dell AX510/AX510PA Flat Panel Soundbar Speakers		Optional		

	МТ	DT	SFF		
Dell USB Entry Keyboard with optional palmrest	Optional				
Dell Multimedia Pro Keyboard	Optional				
Dell USB Optical Mouse	Optional				
Dell Laser Mouse	Optional				

SECURITY

	МТ	DT	SFF
Chassis Intrusion Switch	Optional		
Chassis lock slot and loop support	ock slot and loop support Standard		
Dell Data Protection Hardware Encryption Engine	nal. Available in Q3	3 2011	

SOFTWARE

	МТ	DT	SFF
Dell Client Manager	Available via Dell.com		
Dell Data Protection Access (DDPA)	Standard		

ENVIRONMENTAL

NOTE: For more details on Dell Environmental features, please to go to Environmental Attributes section. See your specific region for availability.

	МТ	DT	SFF
Sustainable packaging	Х	Х	Х
MultiPack packaging	Optional, US only		
Energy Efficient Power Supply	Optional		

ALL-IN-ONE STANDS AND MOUNTS

	МТ	DT	SFF
Small Form Factor AIO Stand			Optional

SERVICE AND SUPPORT

NOTE: For more details on Dell Service Plans please to go to: <u>www.dell.com/service/service_plans</u>

	МТ	DT	SFF
3 Year Warranty ¹ Next Business Day On-site ² (3-3-3)	Standard		
ProSupport	Optional		

¹ For a copy of our guarantees or limited warranties, please write Dell USA L.P., Attn: Warranties, One Dell Way, Round Rock, TX 78682. For more information, visit www.dell.com/warranty.

² Service may be provided by third-party. Technician will be dispatched if necessary following phone-based troubleshooting. Subject to parts availability, geographical restrictions and terms of service contract. Service timing dependent upon time of day call placed to Dell. U.S. only.

DETAILED ENGINEERING SPECIFICATIONS

SYSTEM DIMENSIONS (PHYSICAL)

NOTE: System Weight and Shipping Weight is based on a typical configuration and may vary based on PC configuration. A typical configuration includes: integrated graphics, one hard drive, one optical drive.

	МТ	DT	SFF
	/*11		566
Chassis Volume (liters)	26.27	15.06	8.38
Chassis Weight (pounds/kilograms)	19.55 / 8.87	16.67 / 7.56	12.57 / 5.70
Chassis Dimensions: (HxWxD)			-
Height (inches/centimeters)	14.17 / 36	14.17 / 36	11.42 / 29
Width (inches/centimeters)	6.89 / 17.5	4.02 / 10.2	3.65 / 9.26
Depth (inches/centimeters)	16.42 / 41.7	16.14 / 41	12.28/31.2
Shipping Weight (pounds/kilograms - includes packaging materials)	23.45 / 10.64	20.03 / 9.09	15.2 / 6.89
Packaging Parameters (HxWxD)	·		
Height (inches/centimeters)	21.31/54.13	21.31 / 54.13	19.25/48.90
Width (inches/centimeters)	18.75/47.63	18.75/47.63	15.81/40.16
Depth (inches/centimeters)	14.09 / 35.79	10.84/27.53	10.19/25.88

SYSTEM EXPANSION SLOTS

	мт	DT	SFF
PCIe x16 Slots (Voltage supported 3.3V/12V)	1	1	1
Height (inches/centimeters)	4.376 / 11.115	2.731 /6.89	2.731 /6.89
Length (inches/centimeters)	7.4 / 24.13*	6.6 /16.765	6.6/16.765
Maximum Wattage	75W	25W	25W
PCIe x1 Slots (Voltage supported 3.3V/12V)	3	3	1
Height (inches/centimeters)	4.376 / 11.115	2.731 / 6.89	2.731 / 6.89
Length (inches/centimeters)	7.4 / 24.13*	6.6 /16.765	6.6 /16.765
Maximum Wattage	25W	10W	10W

SYSTEM LEVEL ENVIRONMENTAL AND OPERATING CONDITIONS

	МТ	DT	SFF				
Temperature							
Operating	10° t	o 35° C (50° to	95° F)				
Non-Operating (Storage)	-40° to	o 65° C (-40° to	149° F)				
Relative Humidity	20% to	80% (non-con	densing)				
Maximum vibration							
Operating	0.25 G at 3	to 200 Hz at 0.	5 octave/min				
Non-Operating	0.5 G at 3 to 200 Hz at 1 octave/min						
Maximum Shock							
Operating		-sine pulse wit 50.8 cm/sec (20					
Non-Operating	27-G faired square wave with a velocity change of 508 cm/sec (200 inches/sec)						
Maximum Altitude							
Operating	-15.2 to 3048 m (-50 to 10,000 ft)						
Non-Operating	-15.2 to 10,668 m (-50 to 35,000 ft)						

POWER

NOTE: These form factors utilize a more efficient Active Power Factor Correction (APFC) power supply. Dell recommends only Universal Power Supplies (UPS) based on Sine Wave output for APFC PSUs, not an approximation of a Sine Wave, Square Wave, or quasi-Square Wave. If you have questions, please contact the manufacture to confirm the output type.

	МТ			DT		SFF	
	APFC		APFC	EPA	APFC	EPA	
Power Supply Wattage	265W	265W High Efficiency	250W	250W High Efficiency	240W	240W High Efficiency	
AC input Voltage Range	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac	90 – 264Vac	
AC input current (low ac range/high AC range)	5.0A / 2.5A	5.0A / 2.5A	4.4A / 2.2A	4.4A / 2.2A	4.0A / 2.0A	4.0A / 2.0A	
AC input Frequency	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	47HZ/63HZ	
AC holdup time (80% load)	16MSEC	16MSEC	16MSEC	16MSEC	16MSEC	16MSEC	
Average Efficiency (Energy Star 5.0 Compliant)		87 – 90 – 87% @ 20 – 50 – 100% load		87 - 90 - 87% @ 20 - 50 - 100% load		87 – 90 – 87% @ 20 – 50 – 100% load	
Typical Efficiency (Active PFC)	65%		65%		65%		
DC parameters							
+3.3v output	10.0A	10.0A	7.0 A	7.0 A	3.5A	3.5A	
+5.0v output	13A	13A	15A	15A	11A	11A	
+12.0v output	12VA/17A; 12VB/9A	12VA/17A; 12VB/9A	17.8A	17.8A	17A	17A	
+5.0v auxiliary output	4.0A	4.0A	4.0A	4.0A	4.0A	4.0A	
-12.0v output	0.5A	0.5A	0.5A	0.5A	0.5A	0.5A	
Max total power	265W	265W	255W	255W	235W	235W	
Max combined +3.3v / +5.0v power	90W	90W	90W	90W	60W	60W	
Max combined 12.0v power (note: only if more than one 12v rail)	240W	240W	N/A	N/A	N/A	N/A	
BTUs/h (based on PSU max wattage)	904 BTU	904 BTU	853 BTU	853 BTU	819 BTU	819 BTU	
Power Supply Fan	80*25mm	80*25mm	80*20/25mm	80*20/25mm	60*25mm	60*25mm	
Compliance:							
1watt requirement	Yes	Yes	Yes	Yes	Yes	Yes	
Blue Angel Compliant	Yes	Yes	Yes	Yes	Yes	Yes	
Climate Savers / 80Plus Compliant	No	Yes	No	Yes	No	Yes	
FEMP (CECP) Standby Power Compliant	Yes	Yes	Yes	Yes	Yes	Yes	

POWER

NOTE: These form factors utilize a more efficient Active Power Factor Correction (APFC) power supply. Dell recommends only Universal Power Supplies (UPS) based on Sine Wave output for APFC PSUs, not an approximation of a Sine Wave, Square Wave, or quasi-Square Wave. If you have questions, please contact the manufacture to confirm the output type.

3.0v CMOS battery (Type and estimated battery life)							
Brand	Туре	Voltage	Composition	Life			
JHT	CR-2302L/ BE	3V	Lithium	Continuous Discharge Under 15 k Ω Load to 2.0V End-Voltage. 20°C \pm 2°C.940Hrs. or Longer.910Hrs.or Longer after 12 months.			
MITSUBISHI	CR2302	3V	Lithium	Continuous Discharge Under 15 kΩ Load to 2.0V End- Voltage. 20°C±2°C.940Hrs. or Longer.910Hrs.or Longer after 12 months. 0°C±2°C. 850Hrs. or Longer.820Hrs.or Longer after 12 months.			

AUDIO

INTEGRATED CONEXANT CX20641 HIGH DEFINITION AUDIO	МТ	DT	SFF	
High Definition Stereo support	Х	Х	Х	
Number of channels		2		
Number of Bits / Audio resolution	16, 20	, and 24-bit re	solution	
Sampling rate (recording/playback)	Support 44.	1K/48K/96K/19 rates	92 kHz sample	
Signal to Noise Ratio	98 dB DAC	outputs, 90 d puts	B for ADC in-	
Analog Audio	Х	Х	Х	
Dolby Digital				
ТНХ				
Digital out (S/PDIF)				
Audio Jack Impedance	-			
Microphone	40	0K ohm~60K d	ohm	
Line-In	40	0K ohm~60K d	ohm	
Line-Out		100~150 ohr	n	
Headphone		1~4 ohm		
Internal Speaker Power Rating	2Watt	(peak) / 1Watt	(average)	

COMMUNICATIONS - NETWORK ADAPTER (NIC)

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

INTEGRATED REALTEK® RTL8111E-VL ETHERNET LAN 10/100/1000	мт	DT	SFF	
External Connector Type		RJ45		
Data Rates supported	:	10/100/1000 Mbps		
Controller Details				
Controller bus architecture	PCIe-based int	erface for S0 sta low power state		
Integrated memory		N/A		
Data transfer mode (example Bus-Master DMA)		N/A		
Power consumption (full operation per data rate connection speed)		448.8mW (Max.)	
Power consumption (standby operation)		389.4mW (Max.))	
IEEE standards compliance (example 802.1P)		802.3		
Hardware Certifications (example FCC, B, GS mark)		N/A		
Boot ROM Support	EEF	PROM (located in	SPI)	
Network Transfer Mode (example Full Duplex, Half Duplex)				
Network Transfer Rate (example 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps	10 Mb (full/half-duplex) 100 Mb (full/half-duplex) 1000 Mb (full-duplex)			

COMMUNICATIONS - NETWORK ADAPTER (NIC) (CONT.)

INTEGRATED REALTEK® RTL8111E-VL ETHERNET LAN 10/100/1000	мт	DT	SFF	
Environmental				
Operating temperature	0° C to 70° C (32° F to 158° F)			
Operating humidity	20% to 80% (non-condensing)			
Operating System Driver Support	Windows 7 32/64, Windows XP 32/64, Vista 32/64			
Manageability (examples WOL, PXE)	WOL, PXE 2.1			

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

COMMUNICATIONS - INTEGRATED LAN

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

Broadcom NetXtreme 10/100/1000 PCIe Gigabit ¹ Networking Card	МТ	DT	SFF		
Connector Type		RJ45			
Data Rates supported	10/100/10	10/100/1000 Mbps Half/Full duplex			
Controller Details					
Controller bus architecture (example PCIe 1.0a x1)		PCle c1.0a x1			
Integrated memory	64KB	ytes RX, 8KByte	es TX		
Data transfer mode (example Bus-Master DMA)	В	us-Master DM	4		
Power consumption (full operation per data rate connection speed)	2.84\	N (860mA @ +	3.3V)		
Power consumption (standby operation)	Le	ess than 300m	N		
IEEE standards compliance (example 802.1P)	802.3,	802.2, 802.3x,	802.1p		
Hardware Certifications (example FCC, B, GS mark)	FC	CC B, VCCI B, C	E		
Boot ROM Support		No			
Network Transfer Mode (example Full Duplex, Half Duplex)					
Network Transfer Rate (example 10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps	100BASE-T 100BASE-TX	10BASE-T (full-duplex) 20 Mbps M 100BASE-TX (half-duplex) 100 Mb Max* 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mb Max*			

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

COMMUNICATIONS - INTEGRATED LAN (CONT.)

BROADCOM NETXTREME 10/100/1000 PCIE GIGABIT ¹ NETWORKING CARD (CONT.)	МТ	DT	SFF
Environmental			
Operating temperature	0° C to	o 55° C (32° F -	131° F)
Operating humidity	5% ~ 85% (non-condensing)		
Operating System Driver Support	Windows® 7, Windows® XP, Windo Vista® Ultimate, Windows Vista® Bu ness 32 bit/64 bit, Windows Vista Ho Basic, Linux		Vista® Busi-
Manageability (examples WOL, PXE)	W	OL, PXE2.1, AC	PI
Management Capabilities Alerting (example ASF 2.0)		None	

¹ This term does not connote an actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and

COMMUNICATIONS - WIRELESS

DELL WIRELESS 1520 PCIE WLAN CARD (MT, DT, SFF) 802.11N	мт	DT	SFF	
External Connector Type	Custom WLAN Antenna Connector			
Controller Details				
Controller bus architecture	-	mpatible with the P on v1.1 (x1 lane) and	-	
WLAN standards supported	802.11	a, 802.11b, 802.11g,	802.11n	
802.11b Data Rates supported		11, 5.5, 2, 1 Mbps		
802.11a Data Rates supported	54, 4	8, 36, 24, 18, 12, 9, 6	5 Mbps	
802.11g Data Rates supported	54, 4	8, 36, 24, 18, 12, 9, 6	5 Mbps	
802.11n Data Rates supported	300, 270, 243, 240, 180, 150, 144, 135, 130, 120, 117 115.5, 90, 86.667, 72.2, 65, 60, 57.8, 45, 43.3, 30, 28.4 21.7, 15, 14.4, 7.2 Mbps			
Encryption	WEP 64-bit and 128-bit, TKIP, AES-CCMP 128-bit			
Operating temperature		0 to +70 °C		
Operating humidity	Max Operating Humidity 85 %			
Operating System Driver Support	Windows 7 32,	64, Windows XP 32	/64, Vista 32/64	

COMMUNICATIONS - USB 3.0 ADD-IN CARD

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

USB 3.0 PORT PCIE ADD-IN CARD	МТ	DT	SFF	
Connector Type	PCI Express Gen. 2.0 X1			
Controller Details				
Controller bus architecture (example PCIe 1.0a x1)	PCI Express one lane (x1)			
Chipset	NEC µPD720200			
IO Ports	2 * USB3.0 port			
Power Consumption	Under 30 mA			
Connector	USB 3.0 A Type			
Full height USB3.0 add-in card	Optional			
Half height USB3.0 add-in card		Opti	onal	
OS Support	W	in XP, Win Vista and V	Vin 7	

COMMUNICATIONS - SERIAL / PARALLEL PORT PCIE ADD-IN CARD

NOTE: MT supports full height (FH) card.

SERIAL / PARALLEL PORT PCIE ADD-IN CARD	МТ	DT	SFF
Connector Type	RS-232 and IEEE1284		
Data Rates supported	50bps ~115.2Kbps (Serial) &Maximum 1.8MBp(Parall		
Controller Details			
Controller bus architecture (example PCIe 1.0a x1)	PC	CI Express one lane (x1	L)
Driver Support	Microsoft Se Microsoft Embec Er	ft Client XP/Vista/7 (X& erver 2000/2003/2008 Ided XP Embedded/PC nbedded System 2009 .inux Linux 2.4.x/2.6.x DOS DOS	8 (X86/X64) OS Ready 2009/
Full height Serial / Parallel add-in card	Optional		
Environment			
Operation Temperature	C	to 60°C (32 to 140°F)	
Operation Humidity		5 to 95% RH	
Storage Temperature	-2	0 to 85°C (-4 to 185°F	-)

LOW PROFILE PARALLEL PORT PCIE ADD-IN CARD	МТ	DT	SFF		
Connector Type		IEEE1284			
Data Rates supported		Maximum 1.8MBp			
Controller Details	÷				
Controller bus architecture (example PCIe 1.0a x1)	PC	CI Express one lane (x1	L)		
Driver Support	Microsoft Se Microsoft Embec Er	ft Client XP/Vista/7 (X8 erver 2000/2003/2008 Ided XP Embedded/PC mbedded System 2009 inux Linux 2.4.x/2.6.x DOS DOS	8 (X86/X64) OS Ready 2009/		
Low Profile Parallel add-in card		Optio	nal		
Environment					
Operation Temperature	C	to 60°C (32 to 140°F)			
Operation Humidity		5 to 95% RH			
Storage Temperature	-2	:0 to 85°C (-4 to 185°F	-)		

COMMUNICATIONS-PS2/SERIAL ADD IN DONGLE

NOTE: MT supports full height (FH) dongle and DT and SFF supports low profile (LP) dongle.

PS2/SERIAL ADD IN DONGLE	МТ	DT	SFF
Connector type	RS232 and PS2		
Controller Details	•		
Interface type	24 pins	header connect to M	1B directly
IO Ports	1 Serial, 2 PS2		
Full height PS2/Serial add in dongle	Optional		
Half height PS2/Serial add in dongle		Opti	onal
Environment			
Operation Temperature	0°	C to 70° C (32° F to 1	58° F)
Operation Humidity	205	% to 80% (non-conde	nsing)
Storage Temperature		-20 to 85°C (-4 to 18	5°F)

GRAPHICS/VIDEO CONTROLLER

NOTE: MT supports full height (FH) cards and DT and SFF supports low profile (LP) cards.

Owners of Cranchica				
Onboard Graphics.	мт	DT	SFF	
1. Intel HD Graphics [with Celeron/Pentium class CPU-GPU combo]	1011		JLL	
2. Intel HD Graphics 2000 [with iCore Dual/Quad core class CPU-GPU combo]				
Bus Type	Integrated			
GPU core clock		tel® HD Graphic s 2000 @ 850M		
Frame Buffer Memory (onboard and shared) Size and Speed		available system with 4GB system		
Overlay Planes	Yes			
Maximum Color Depth		32 bit		
Maximum Vertical Refresh Rate	75 Hz			
Multiple Display Support		Yes		
Operating Systems Graphics/ Video API Support	Ope	nGL 3.0/DirectX	10.1	
Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital)		20x1200 @ 60H 048x1536 @ 75F		
External Connectors		VGA, HDMI		
НДМІ				
Bus Type		DDPD		
Maximum supported resolution	Up to	o 1920x1200 @	60Hz	
Maximum power consumption		N/A		
Audio Support	Yes (Only	for native HDM	II Output)	
External connectors		HDMI		

¹Up to 1.7 GB of system memory may be allocated to support integrated graphics, depending on operating system, system memory size and other

factors. ² DVI and VGA can be used concurrently for multi-monitor display in DOS. The DisplayPort controller does not support multi-monitor display in

GRAPHICS/VIDEO CONTROLLER (CONT.)

1GB AMD RADEON™ HD6450	МТ	DT	SFF	
Bus Type (example integrated or PCIe x16)		PCIEx16		
GPU core clock		625Mhz		
Frame Buffer Memory (onboard and shared) Size and Speed		800Mhz		
Maximum power consumption		20W		
Overlay Planes		Yes		
Maximum Color Depth		32-bit		
Maximum Vertical Refresh Rate	85Hz			
Multiple Display Support		Yes		
Operating Systems Graphics/ Video API Support		D3D and OpenG	L	
Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital)	DispalyPo VGA N	0VI Max: 2560 x 1600 rt Max: 2560 x 1600/ 1ax : 1920x1440/32b in : 640x480/8bpp @	32bpp @ 75Hz pp @ 75Hz	
External connectors		/I-I and 1 DP or 1 VG		
Audio Support		ve DP). Able to suppo gle that supports audi		
Dimensions of full height card inches/centimeters (L x H)	6.6 x 4.7 / 16.764 x 12.0		o pass through.	
Dimensions of low profile card inches/centimeters (L x H)		6.6 x 3.35 /	16.764 x 8.5	
Environmental Operating Conditions (Non-Condensing):				
Operating Temperature Range		10°-50° C		
Relative Humidity Range		5-90% RH		
	0-20,000 ft.			
Altitude Range		0-20,000 ft.		
512MB AMD RADEON™ HD6350	MT	0-20,000 ft. DT	SFF	
512MB AMD RADEON™ HD6350	MT		SFF	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16)	MT	DT	SFF	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock	MT	DT PCIEx16	SFF	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed	MT	DT PCIEx16 650Mhz	SFF	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption	MT	DT PCIEx16 650Mhz 800Mhz	SFF	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes	MT	DT PCIEx16 650Mhz 800Mhz 20W	SFF	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes	MT	DT PCIEx16 650Mhz 800Mhz 20W Yes	SFF	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate	MT	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit	SFF	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support	MT	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit 85Hz Yes		
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate	DVI M VGA M	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit 85Hz Yes D3D and OpenGi lax : 1920x1200/32bp Aax: 1920x1440/32bp	- pp @ 75Hz pp @ 75Hz	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital)	DVI M VGA M	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit 85Hz Yes D3D and OpenGil lax : 1920x1200/32bp	- op @ 75Hz op @ 75Hz o 60Hz	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital) External connectors	DVI M VGA M	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit 85Hz Yes D3D and OpenGil lax : 1920x1200/32bp Max: 1920x1440/32bp in : 640x480/8bpp @	- op @ 75Hz op @ 75Hz o 60Hz	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support	DVI M VGA M	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit 85Hz Yes D3D and OpenGi lax : 1920x1200/32bp Aax: 1920x140/32bp in : 640x480/8bpp @ DMS59 (DVI x2 or VC	- pp @ 75Hz pp @ 75Hz 0 60Hz	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCle x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital) External connectors Audio Support Dimensions of full height card inches/centimeters (L x H)	DVI M VGA M VGA M 1 6.6 x 2.731 / 16.764 x	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit 85Hz Yes D3D and OpenGi lax: 1920x1200/32bp Max: 1920x140/32bp in : 640x480/8bpp @ DMS59 (DVI x2 or VC No	- op @ 75Hz op @ 75Hz o 60Hz	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital) External connectors Audio Support Dimensions of full height card inches/centimeters (L x H)	DVI M VGA M VGA M 1 6.6 x 2.731 / 16.764 x	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit 85Hz Yes D3D and OpenGi lax: 1920x1200/32bp Max: 1920x140/32bp in : 640x480/8bpp @ DMS59 (DVI x2 or VC No	L pp @ 75Hz pp @ 75Hz o 60Hz GA x2)	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCIe x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital) External connectors Audio Support Dimensions of full height card inches/centimeters (L x H) Dimensions of low profile card inches/centimeters (L x H) Environmental Operating Conditions (Non-Condensing):	DVI M VGA M VGA M 1 6.6 x 2.731 / 16.764 x	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit 85Hz Yes D3D and OpenGi lax: 1920x1200/32bp Max: 1920x140/32bp in : 640x480/8bpp @ DMS59 (DVI x2 or VC No	L pp @ 75Hz pp @ 75Hz o 60Hz GA x2)	
512MB AMD RADEON™ HD6350 Bus Type (example integrated or PCle x16) GPU core clock Frame Buffer Memory (onboard and shared) Size and Speed Maximum power consumption Overlay Planes Maximum Color Depth Maximum Vertical Refresh Rate Multiple Display Support Operating Systems Graphics/ Video API Support Supported Resolutions and Max Refresh Rates (Hz) (Note: Analog and/or digital) External connectors Audio Support Dimensions of full height card inches/centimeters (L x H) Dimensions of low profile card inches/centimeters (L x H)	DVI M VGA M VGA M 1 6.6 x 2.731 / 16.764 x	DT PCIEx16 650Mhz 800Mhz 20W Yes 32-bit 85Hz Yes D3D and OpenGi lax: 1920x1200/32bp Max: 1920x140/32bp in : 640x480/8bpp @ DMS59 (DVI x2 or VC No 6.6 x 2.731 / 1	L pp @ 75Hz pp @ 75Hz o 60Hz GA x2)	

HARD DRIVES¹

3.5″ 1TB SATA 7200 RPM HDD	
Capacity (bytes)	1,000,204,886,016
Dimensions inches (W x D x H)	5.87 x 4 x 1
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0) Up to 3Gb/s (SATA 2.0)
Internal buffer size	32 MB
Average Seek Time	8.5 ms
Rotational Speed	7200 rpm
Logical Blocks	1,953,525,168
Power Source	
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)
Spin Up Current (reference only)	5V (1A) ,12V (2A)
Environmental Operating Conditions (Non-Condensing):	
Temperature Range	5°C to 60°C
Relative Humidity Range	20% to 80% non-condensing
Maximum Wet Bulb Temperature	29 ⁰ C
Altitude Range	-50 ft to 10000 ft
Environmental Non-Operating Conditions (Non-Condensing):	
Temperature Range	-40°C to 65°C
Relative Humidity Range	10% to 90% non-condensing
Maximum Wet Bulb Temperature	38 ⁰ C
Altitude Range	-50 ft to 35000 ft

HARD DRIVES¹ (CONT.)

3.5″ 500GB SATA 7200 RPM HDD		
Capacity (bytes)	500,107,862,016	
Dimensions inches (W x D x H)	5.87 x 4 x 1	
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0) Up to 3Gb/s (SATA 2.0)	
Internal buffer size	16 MB	
Average Seek Time	8.5 ms	
Rotational Speed	7200 rpm	
Logical Blocks	976,773,168	
Power Source		
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)	
Spin Up Current (reference only)	5V (1A) ,12V (2A)	
Environmental Operating Conditions (Non-Condensing):		
Temperature Range	5°C to 60°C	
Relative Humidity Range	20% to 80% non-condensing	
Maximum Wet Bulb Temperature	29°C	
Altitude Range	-50 ft to 10000 ft	
Environmental Non-Operating Conditions (Non-Condensing):		
Temperature Range	-40°C to 65°C	
Relative Humidity Range	10% to 90% non-condensing	
Maximum Wet Bulb Temperature	38°C	
Altitude Range	-50 ft to 35000 ft	

HARD DRIVES¹ (CONT.)

3.5" 320GB SATA 7200 RPM HDD		
Capacity (bytes)	320,072,933,376	
Dimensions inches (W x D x H)	5.87 x 4 x 1	
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0) Up to 3Gb/s (SATA 2.0)	
Internal buffer size	16 MB	
Average Seek Time	8.5 ms	
Rotational Speed	7200 rpm	
Logical Blocks	625,142,448	
Power Source		
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)	
Spin Up Current (reference only)	5V (1A) ,12V (2A)	
Environmental Operating Conditions (Non-Condensing):		
Temperature Range	5 ⁰ C to 60 ⁰ C	
Relative Humidity Range	20% to 80% non-condensing	
Maximum Wet Bulb Temperature	29 ⁰ C	
Altitude Range	-50 ft to 10000 ft	
Environmental Non-Operating Conditions (Non-Condensing):		
Temperature Range	-40°C to 65°C	
Relative Humidity Range	10% to 90% non-condensing	
Maximum Wet Bulb Temperature	38°C	
Altitude Range	-50 ft to 35000 ft	

HARD DRIVES¹ (CONT.)

3.5″ 250GB SATA 7200 RPM HDD	
Capacity (bytes)	250,059,350,016
Dimensions inches (W x D x H)	5.87 x 4 x 1
Interface type and Maximum speed	Up to 6Gb/s (SATA 3.0) Up to 3Gb/s (SATA 2.0)
Internal buffer size	8 MB
Average Seek Time	8.5 ms
Rotational Speed	7200 rpm
Logical Blocks	488,397,168
Power Source	
Power Consumption (reference only)	Idle 5.0W, Active 10.0W(running IOmeter utility)
Spin Up Current (reference only)	5V (1A) ,12V (2A)
Environmental Operating Conditions (Non-Condensing):	
Temperature Range	5°C to 60°C
Relative Humidity Range	20% to 80% non-condensing
Maximum Wet Bulb Temperature	29 ⁰ C
Altitude Range	-50 ft to 10000 ft
Environmental Non-Operating Conditions (Non-Condensing):	
Temperature Range	-40°C to 65°C
Relative Humidity Range	10% to 90% non-condensing
Maximum Wet Bulb Temperature	38°C
Altitude Range	-50 ft to 35000 ft

OPTICAL DRIVES

DVD +/- RW ¹	МТ	DT	SFF
External Dimensions inches/ centimeters (Without Bezel – W x H x D)	148.2mm(6in)/42mm (2in)/ 190.5 (max)	148.2mm(6in)/42mm (2in)/ 190.5 (max)	128.0 mm (5.04)/ 12.7mm (0.5 in)/ 126.1mm (4.97in)
Weight (max) pounds/kilograms	800g	800g	170g
Interface type and speed	SATA 1.5Gbit/s	SATA 1.5Gbit/s	SATA 1.5Gbit/s
Disc Capacity	Standard	Standard	Standard
Internal buffer size	supplier dependent	supplier dependent	supplier dependent
Access Times (typical)	supplier dependent	supplier dependent	supplier dependent
Maximum Data Transfer Rates			
Writes	16x DVD/48x CD	16x DVD/48x CD	8x DVD/ 24x CD
Reads	16x DVD/48x CD	16x DVD/48x CD	8x DVD/ 24x CD
Power Source			
DC Power Requirements	12V, 5V	12V, 5V	5V
DC Current	1200mA (12V)/ 900mA (5V)	1200mA (12V)/ 900mA (5V)	1000mA
Environmental Operating Condition	ons (Non-Condensing):		
Operating Temperature Range	5C to 50C	5C to 50C	5C to 50C
Relative Humidity Range	20% to 80% RH	20% to 80% RH	20% to 80% RH
Maximum Wet Bulb Temperature	29C	29C	29C
Altitude Range	-200 to 3048	-200 to 3048	-200 to 3048
Environmental Non-Operating Conditions (Non-Condensing):			
Operating Temperature Range	-40C to 65C	-40C to 65C	-40C to 65C
Relative Humidity Range	5% to 95% RH	5% to 95% RH	5% to 95% RH
Maximum Wet Bulb Temperature	38C	38C	38C
Altitude Range	-200 to 10600m	-200 to 10600m	-200 to 10600m

¹ Discs burned with this drive may not be compatible with some existing drives and players; using DVD+R media provides maximum compatibility.

DVD-ROM	МТ	DT	SFF
External Dimensions inches/ centimeters (Without Bezel – W x H x D)	148.2mm(6in)/42mm (2in)/ 190.5 (max)	148.2mm(6in)/42mm (2in)/ 190.5 (max)	128.0 mm (5.04)/ 12.7mm (0.5 in)/ 126.1mm (4.97in)
Weight (max) pounds/kilograms	750g	750g	165g
Interface type and speed	SATA 1.5Gbit/s	SATA 1.5Gbit/s	SATA 1.5Gbit/s
Disc Capacity	Standard	Standard	Standard
Internal buffer size	supplier dependent	supplier dependent	supplier dependent
Access Times (typical)	supplier dependent	supplier dependent	supplier dependent
Maximum Data Transfer Rates			
Writes	N/A	N/A	N/A
Reads	16x DVD/48x CD	16x DVD/48x CD	8x DVD/ 24x CD

OPTICAL DRIVES (CONT.)

DVD-ROM (CONT.)	МТ	DT	SFF	
Power Source	Power Source			
DC Power Requirements	12V, 5V	12V, 5V	5V	
DC Current	1200mA (12V)/ 900mA (5V)	1200mA (12V)/ 900mA (5V)	800mA	
Environmental Operating Condition	ons (Non-Condensing):			
Operating Temperature Range	5C to 50C	5C to 50C	5C to 50C	
Relative Humidity Range	20% to 80% RH	20% to 80% RH	20% to 80% RH	
Maximum Wet Bulb Temperature	29C	29C	29C	
Altitude Range	-200 to 3048m	-200 to 3048m	-200 to 3048m	
Environmental Non-Operating Conditions (Non-Condensing):				
Operating Temperature Range	-40C to 65C	-40C to 65C	-40C to 65C	
Relative Humidity Range	5% to 95% RH	5% to 95% RH	5% to 95% RH	
Maximum Wet Bulb Temperature	38C	38C	38C	
Altitude Range	-200 to 10600m	-200 to 10600m	-200 to 10600m	

MEDIA CARD READER (MCR)

NOTE: Dell 19 in 1 Media Card Reader (MCR) is supported via a F5 to F3 bay converter on the MT and DT and may require a slim line optical drive depending on selectable configuration. MCR is not available on the SFF and USFF chassis.

19 IN 1 MEDIA CARD READER	MT/DT
External Dimensions inches/(centimeters) (With Bezel – W x H)	3.99/(10.13cm)/1.0/(2.54cm)
Weight (max) pounds/kilograms	~155g
Interface type and speed	USB 2.0, 480Mb/s
Media Supported (maximum capacity supported will vary by F	lash Media Types)
Media Supported	CF I CF II Micro Drive (MD) Secure Digital (SD) SDHC Mini Secure Digital (mini-SD) Micro Secure Digital (Micro-SD)(with adapter) Multi Media Card (MMC) RS Multi Media Card (MMC) Multi Media Card plus (MMC plus) RS Multi Media Card plus (MMC plus) RS Multi Media Card plus (RS-MMC plus) Multi Media Card Nicro) (MXC plus) Multi Media Card Discon (MS-Dus) Memory Stick Pro Duo (MS Pro Duo) Memory Stick Pro Duo (MS-Duo) Memory Stick Micro)(M2) (with adapter) Smart Media (SM) xD
Support Specification Versions:	Compact Flash type I/II Version 4.0 Smart Media (SM) Specification 2003 Multi Media Card (MMC) Specification 4.2 Secure Digital (SD) 2.0 Memory Stick Pro (MS-PRO) Specification 1.02 Memory Stick (MS) Specification 1.43 xD Specification 1.2
Power Source	·
Max Power Requirements	2.5W
Supply Voltage Range	4.75V ~ 5.25V
Power Consumption:	Standby less than 0.5mA @ 5.0VDC
Environmental Operating Conditions (Non-Condensing):	
Operating Temperature Range	5C to 50C
Relative Humidity Range	10% to 90% RH
Environmental Non-Operating Conditions (Non-Condensing):
Operating Temperature Range	-40C to 65C
Relative Humidity Range	5% to 95% RH

BIOS DEFAULTS

System Configuration	Integrated NIC:	Enabled
	SATA Operation:	ATA
	Drives:	Enable (SATA-0, SATA-1, SATA-2, SATA- 3)
	SMART Reporting:	Disable
		Enable or Disable the integrated USB Controller for Boot Support, Front USB,
	USB Controller:	Rear Dual USB, Rear Quad USB
	Miscellaneous Devices:	
Video	Multi-Display:	Disable
Performance	Multiple Core Support:	All
	listel@ CasedCtesTM:	Freeble
	Intel® SpeedStep™: C States Control:	Enable Enable
	HyperThread control:	Enable
	HDD Protection Support	Disable
	HDD Protection support	Disable
Virtualization Support	Virtualization:	Enable
	VT for Direct I/O:	Enable
•		
Security	Strong Password:	Disable
	Password Configuration:	Min/Max: 4/32
	Password Bypass:	Disable
	Password Changes:	Enable
	Computrace®:	Deactivate
	Chassis Intrusion:	Disable
	CPU XD Support:	Enable
Power Management	AC Recovery:	Power Off
	Auto On Time:	Disable
	Deep Sleep Control:	Disable
	Fan Control Override:	Disable
	Wake on LAN:	Disable
Maintenance	Service Tag:	Set by the factory
	Asset Tag:	Optional User Entry
	SERR Message:	Enable
	Number de LED	Freekla
POST Behavior	Numlock LED:	Enable
	Keyboard Errors:	Enable
	POST HotKeys:	Enable
	Fast Boot:	Thorough

CHASSIS ENCLOSURE & VENTILATION REQUIREMENTS

ENCLOSURE VENTILATION

If your enclosure has doors, they need to be of a type that allows at least 30% airflow through the enclosure (front and back).

ENCLOSURE MINIMUM CLEARANCE

Leave a 10.2 cm (4 in.) minimum clearance on all vented sides of the computer to permit the airflow required for proper ventilation.

RECOMMENDED ENCLOSURE

Do not install your computer in an enclosure that does not allow airflow. This restricts the airflow and impacts your computer's performance, possibly causing it to overheat.

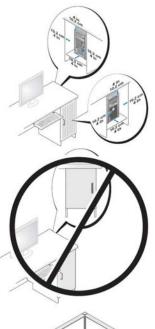
OPEN DESK MINIMUM CLEARANCE

If your computer is installed in a corner, on a desk, or under a desk, leave at least 5.1 cm (2 in.) clearance from the back of the computer to the wall to permit the airflow required for proper ventilation.

REGULATORY COMPLIANCE AND ENVIRONMENTAL

Product related conformity assessment and regulatory authorizations including Product Safety, Electromagnetic Compatibility (EMC), Ergonomics, and Communication Devices relevant to this product may be viewed at www.dell.com/ regulatory_compliance. The Regulatory Datasheet for this product is located at http://www.dell.com/regulatory_compliance.

Details of Dell's environmental stewardship program to conserve product energy consumption, reduce or eliminate materials for disposal, prolong product life span and provide effective and convenient equipment recovery solutions may be viewed at www.dell.com/environment. Product related conformity assessment, regulatory authorizations, and information encompassing Environmental, Energy Consumption, Noise Emissions, Product Materials Information, Packaging, Batteries, and Recycling relevant to this product may be viewed by clicking the Design for Environment link on the webpage.





OptiPlex 390		
	Reduce energy consumption, save money	Notes
	Energy efficient design: Allowing you compute more, and consume less. The OptiPlex 390 is 5.0 Energy Star® rated (containing a 80 PLUS® Gold certified power supply) which means it uses energy-efficient power supplies, operates efficiently in multiple modes (Off, Sleep and Idle), and has advanced power-management features enabled. This level of efficiency helps you save money and energy associated with the use of your product.	All E-Star Selected configs
	Compare energy consumption with energy savings calculator: www.dell.com/energy	All configs
	Take control of your energy consumption: Includes Energy Smart Power Management Settings which allows you to configure your computer to ensure the greatest energy saving in Inactive mode.	All Energy Smart Selected configs
	Reduce, Re-use, Recycle	
0	Recycle responsibly and invest in peace of mind: Protect your company's sensitive data and recycle responsibly with the Dell Asset Recovery & Recycling Service. Find out how: http://content.dell.com/us/en/enterprise/services-asset-recovery-services.aspx?redirect=2	All configs
	Protect developing countries from e-waste exports: Because responsible recycling matters to you, it matters to us. In 2009, Dell was the first in the industry to ban the export of nonworking electronics or electronic waste (e-waste) to developing countries. Learn more: http://content.dell.com/us/en/corp/d/corp-comm/e-waste.aspx	All configs
	Eco-responsible packaging	
	Molded paper pulp packaging cushions (where available): Making it easier to choose products with eco-responsible packaging, this product is cradled in our innovative molded paper pulp packaging. We know that responsible sourcing is important to you, so our pulp is made with 100% news print or recycled cardboard that is sourced near manufacturing operations to the reduce carbon footprint of shipping.	SFF configs only - regional disclaimer: only available in US, Canada and Malaysia
	Recycled milk jug packaging cushions (where available): Making it easier to choose products with eco-responsible packaging, this product is cradled in our innovative recylced milk jug HDPE packaging. We know that responsible sourcing is important to you, so our cushions are made with 100% recycled material that is sourced near manufacturing operations to the reduce carbon footprint of shipping.	MT and DT configs only - regional disclaimer: only available in US, Canada and Malaysia
8	Recycled packaging: Helping you to avoid sending unnecessary waste to landfills, this products ships with expanded polyethylene cushion packaging material which has a high percentage of recycled content (20% in APJ, 25% in EMEA and 65% in Americas). Using recycled materials encourages waste reduction and the conservation of resources.	USFF and regional configs not shipping HDPE o Molded Paper cushions
	Shipped in recycled materials: To help you reduce waste and reuse potentially useful materials, this product's box packaging is made with at least 25% recycled post consumer cardboard	All configs
	Reduce packaging waste: Dell is implementing a plan to simplify and revolutionize computer packaging that will result in the elimination of approximately 20 million pounds of packaging materials from 2008 through 2012. Find out more: http://content.dell.com/us/en/corp/d/corp-comm/earth-products-packaging.aspx. This product is also offered in a multipack configuration upon request.	All configs. Multipack is available in the US
	Environmentally Preferable Ingredients	
σ.	Finding better ingredients: Making it easy for you to reduce your environmental impact, all OptiPlex 390 enclosure plastics are built with a minimum of 10% Post Consumer Recycled Content. It also has reduced levels of environmentally sensitive materials such as mercury and arsenic	
	Meets or exceeds world-wide environmental standards: WW EU RoHS (Lead free), China RoHS and REACH compliant.	All configs
Eco- Participation	EPEAT US/Canada/France, Energy Star, TCO, Blue Angel Learn more about Eco-Labels at http://content.dell.com/us/en/corp/d/corp-comm/dell-green-product- certifications.aspx	

ACOUSTIC NOISE EMISSION INFORMATION

OPTIPLEX 390 MT

Component	Typical Configuration	High-end Configuration
CPU	Intel i5,3.1GHZ,4c SNB 95W	Intel i5,3.1GHZ,4c SNB 95W
Memory	4GB DDR3 1333MHz	4GB DDR3 1333MHz
HDD (#, capacity)	1TB 7200RPM SATA3	1TB 7200RPM SATA3(x2)
RMSD	16X DVD SATA HH 8X DVD+/-RW SATA 12.7	16X DVD SATA HH 8X DVD+/-RW SATA 12.7
Graphics Adapter	Intel® HD Graphics Family	ATI Radeon HD 6450

The Declared Noise Emission in accordance with ISO 9296 for the Dell OptiPlex 390 MT is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10⁻¹² Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})	High-end Configuration Declared Sound Power (L _{WAd})
Idle	3.4	3.5
HDD Operating	3.6	3.5
90% CPU	3.6	3.5
ODD Operating	5.2	5.2

The Declared A-weighted Sound Pressure Level in decibels (re 2x10⁻⁵ Pa), at Operator, Bystander, and Desk Side Positions are measured in accordance with ISO 7779 7.6.1, 7.6.2, and C.15.2 and declared in accordance with ISO 9296 for this product is as follows¹:

Operating Mode	Typical Configuration Declared Sound Pressure (LpA)				High-end Configuration Declared Sound Pressure (LpA)			
	Table-Top		Floor-Standing		Table-Top		Floor- Standing	
	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)
Idle	23.7	20.2	18.8	19.1	22.9	19.1	18.0	18.8
HDD Operating	24.1	20.5	19.0	19.3	23.3	19.7	18.1	18.9
90% CPU	23.8	20.6	19.3	19.8	24.0	20.2	18.4	18.9
ODD Operating	43.3	36.5	35.2	35.4	43.6	36.8	36.6	35.3

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2

ACOUSTIC NOISE EMISSION INFORMATION

OPTIPLEX 390 DT

Component	Typical Configuration	High-end Configuration Intel i5,3.1GHZ,4c SNB 95W		
CPU	Intel i5,3.1GHZ,4c SNB 95W			
Memory	4GB DDR3 1333MHz	4GB DDR3 1333MHz		
HDD (#, capacity)	1TB 7200RPM SATA3	1TB 7200RPM SATA3		
RMSD	16X DVD+/-RW SATA HH	16X DVD+/-RW SATA HH		
Graphics Adapter	Intel® HD Graphics Family	ATI Radeon HD 6450		

The Declared Noise Emission in accordance with ISO 9296 for the Dell OptiPlex 390 DT is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10⁻¹² Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})	High-end Configuration Declared Sound Power (L _{WAd})		
Idle	3.4	3.4		
HDD Operating	3.4	3.4		
90% CPU	4.0	4.1		
ODD Operating	5.2	5.2		

The Declared A-weighted Sound Pressure Level in decibels (re $2x10^{-5}$ Pa), at Operator, Bystander, and Desk Side Positions are measured in accordance with ISO 7779 7.6.1, 7.6.2, and C.15.2 and declared in accordance with ISO 9296 for this product is as follows¹:

Operating Mode	Typical Configuration Declared Sound Pressure (LpA)				High-end Configuration Declared Sound Pressure (LpA)			
	Table-Top		Floor-Standing		Table-Top		Floor- Standing	
	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)
Idle	24.5	18.4	18.0	19.7	23.8	19.3	18.6	18.6
HDD Operating	24.5	18.4	18.2	19.6	24.1	19.4	18.6	18.7
90% CPU	31.1	22.6	24.0	26.2	32.9	28.0	23.9	22.4
ODD Operating	43.6	34.8	36.0	38.3	43.8	38.4	35.3	34.5

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2

ACOUSTIC NOISE EMISSION INFORMATION

OPTIPLEX 390 SFF

Component	Typical Configuration	High-end Configuration		
CPU	Intel i5,3.1GHZ,4c SNB 95W	Intel i5,3.1GHZ,4c SNB 95W		
Memory	4GB DDR3 1333MHz	4GB DDR3 1333MHz		
HDD (#, capacity)	1TB 7200RPM SATA3	1TB 7200RPM SATA3		
RMSD	8X DVD+/-RW SATA 12.7	8X DVD+/-RW SATA 12.7		
Graphics Adapter	Intel® HD Graphics Family	ATI Radeon HD 6450		

The Declared Noise Emission in accordance with ISO 9296 for the Dell OptiPlex 390 SFF is as follows: (all values L_{WAd} expressed in bels; 1 bel=10 decibels, re 10⁻¹² Watts)

Operating Mode	Typical Configuration Declared Sound Power (L _{WAd})	High-end Configuration Declared Sound Power (L _{WAd})		
Idle	3.7	3.7		
HDD Operating	3.7	3.7		
90% CPU	4.5	4.5		
ODD Operating	4.6	4.6		

The Declared A-weighted Sound Pressure Level in decibels (re 2x10⁻⁵ Pa), at Operator, Bystander, and Desk Side Positions are measured in accordance with ISO 7779 7.6.1, 7.6.2, and C.15.2 and declared in accordance with ISO 9296 for this product is as

Operating Mode	Typical Configuration Declared Sound Pressure (LpA)				High-end Configuration Declared Sound Pressure (LpA)			
	Table-Top		Floor-Standing		Table-Top		Floor- Standing	
	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)	Operator Position (LpA)	Bystander Position (LpA)
Idle	26.1	22.7	19.0	19.2	25.9	22.6	18.8	19.1
HDD Operating	26.0	22.7	19.0	19.4	25.8	22.4	18.8	19.1
90% CPU	33.2	29.7	26.0	25.7	33.4	29.9	24.9	25.3
ODD Operating	36.6	31.1	29.7	28.4	36.7	31.1	29.3	28.6

¹ All tests are conducted according to ISO 7779 and declared according to ISO 9296 except 90% CPU. For this mode, the system CPU was stressed at 90% utilization with no other peripheral device actively seeking. This test mode is not specified in ISO 7779, but was measured using the same microphone distances and measurement techniques defined for the other reported operating modes. ² Declared Sound Power rounded to nearest tenth of a bel per ISO 9296 section 4.4.2